SCAS399A – JANUARY 1992

				SCAS399A -
•	<ul> <li>Members of the Texas Instruments</li> <li>Widebus<sup>™</sup> Family</li> </ul>	16474 WD PACKAGE 16474 DL PACKAGE	(TOP VIE	: MA()
	Packaged in Shrink Small-Outline 300-mil			
	Packages (DL) and 380-mil Fine-Pitch Ceramic Flat Packages (WD) Using 25-mil Center-to-Center Pin Spacings	1 <mark>0EAB</mark> [ 1CLKAB[		56 ] 1 <mark>0EBA</mark> 55 ] 1CLKBA
		1A1[	3	54 🛛 1B1
	3-State Outputs Drive Bus Lines Directly	GND	4	53 🛛 GND
	Flow-Through Architecture Optimizes	1A2[		52 ] 1B2
	Printed Circuit Board (PCB) Layout	1A3[		<sub>51</sub> ] 1B3
	Distributed Vac and GND Bin Configuration	V <sub>CC</sub>		50 VCC
	<ul> <li>Distributed V<sub>CC</sub> and GND Pin Configuration Minimizes High-Speed Switching Noise</li> </ul>	1A4		49 <b>]</b> 1B4
		1A5[		48 ] 1B5
(	■ EPIC <sup>™</sup> (Enhanced-Performance Implanted	1A6		47 ] 1B6
	CMOS) 1-µm Process	GND		46 GND
(	500-mA Typical Latch-Up Immunity at 125°C	1A7		45 ] 1B7
		1A8[ 1A9[		44 ] 1B8 43 ] 1B9
des	cription	2A1		43    1B9 42    2B1
	These devices are non-investing 10 bit registered	2A1 2A2		42    2B1 41    2B2
	These devices are non-inverting 18-bit registered bus transceivers composed of two 9-bit sections	2A3		40 2B3
	with separate control signals. For either 9-bit	GND		39 GND
	transceiver section, data flow in the A-to-B mode	2A4		38 1 2B4
	is controlled by output-enable (10EAB or 20EAB)	2A5		37 1 2B5
	and clock (1CLKAB or 2CLKAB) inputs. When	2A6		36 2B6
	10EAB or 20EAB is low, the corresponding			
	outputs are active (high or low) and take on either	2A7		34 2B7
	the current data on low-to-high transition of	2A8	24	33 <b>5</b> 2B8
	1CLKAB or 2CLKAB or the previously stored data	GND	25	32 GND
	if 1CLKAB or 2CLKAB is low.	2A9	26	31 <b>6</b> 2B9

2A9 26 31 2B9 2CLKAB 27 30 2CLKBA When 10EAB or 20EAB is high, the corresponding outputs are in the high-impedance state. does not affect the operation on the internal registers. Previously stored date can be related or new data can be entered while the outputs are in the high-impedance state.

Data flow from B to A is similar, but uses 10EBA and/or 20EBA and 1 CLKBA and/or 2CLKBA.

The 74AC16474 is packaged in TI's shrink small-outline packages (DL) with 25-mil center-to-center pin spacings. This package provides twice the I/O pin count and functionality of a standard small-outline package in the same PCB area.

The 54AC16474 is characterized over the full military temperature range of  $-55^{\circ}$ C to  $125^{\circ}$ C. The 74AC16474 is characterized for operation from  $-40^{\circ}$ C to  $85^{\circ}$ C.

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SCAS399A – JANUARY 1992

#### FUNCTION TABLE<sup>†</sup>

	INPUTS	OUTPUTS	
CLKAB	OEAB	Α	В
Х	Н	Х	Z
L	L	Х	В <sub>0</sub> ‡
↑	L	н	Н
$\uparrow$	L	L	L

<sup>†</sup> A-to-B data flow is shown. B-to-A data flow is controlled analogously by CLKBA and OEBA. <sup>‡</sup> Level of B before the indicated steady-state input conditions were established.

### logic symbol§



§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



SCAS399A – JANUARY 1992





SCAS399A – JANUARY 1992

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	
Output voltage range, V <sub>O</sub> (see Note 1)	$\dots \dots \dots \dots -0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ )	±20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ )	±50 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V <sub>CC</sub> or GND pins	±450 mA
Storage temperature range	−65°C to 150°C

<sup>+</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp current ratings are observed.

#### recommended operating conditions (see Note 2)

			54	AC1647	4	74	AC1647	4		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC	Supply voltage		3	5	5.5	3	5	5.5	V	
		V <sub>CC</sub> = 3 V	2.1			2.1				
VIH	High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15			3.15			V	
		V <sub>CC</sub> = 5.5 V	3.85			3.85				
		V <sub>CC</sub> = 3 V			0.9			0.9		
VIL	Low-level input voltage	V <sub>CC</sub> = 4.5 V			1.35			1.35	V	
		V <sub>CC</sub> = 5.5 V			1.65			1.65		
VI	Input voltage		0		VCC	0		VCC	V	
Vo	Output voltage		0		VCC	0		VCC	V	
		V <sub>CC</sub> = 3 V			-4			-4		
ЮН	High-level output current	V <sub>CC</sub> = 4.5 V			-24			-24	mA	
		V <sub>CC</sub> = 5.5 V			-24			-24		
		V <sub>CC</sub> = 3 V			12			12		
IOL	Low-level output current	V <sub>CC</sub> = 4.5 V			24			24	mA	
		V <sub>CC</sub> = 5.5 V			24			24		
$\Delta t/\Delta v$	Input transition rise or fall rate	•	0		10	0		10	ns/V	
T <sub>A</sub>	Operating free-air temperature		-55		125	-40		85	°C	

NOTE 2: Unused or floating (input or I/O) must be held high or low

PRODUCT PREVIEW

SCAS399A – JANUARY 1992

			Т	λ = 25°C	54AC16474	74AC16474	
PARAMETER	TEST CONDITIONS	Vcc	MIN	ΤΥΡ ΜΑΧ	MIN MAX	MIN MAX	UNIT
		3 V	2.9		2.9	2.9	
	I <sub>OH</sub> = -50 μA	4.5 V	4.4		4.4	4.4	
		5.5 V	5.4		5.4	5.4	
	$I_{OH} = -4 \text{ mA}$	3 V	2.58		2.4	2.48	
∕он		4.5 V	3.94		3.7	3.8	V
	I <sub>OH</sub> = -24 mA	5.5 V	4.94		4.7	4.8	
	$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V			3.85		
	I <sub>OH</sub> = -75 mA <sup>†</sup>	5.5 V				3.85	
		3 V		0.1	0.1	0.1	0.1 0.1
	I <sub>OL</sub> = 50 μA	4.5 V		0.1	0.1	0.1	
		5.5 V		0.1	0.1	0.1	
	I <sub>OL</sub> = 12 mA	3 V		0.36	0.5	0.44	v
/OL		4.5 V		0.36	0.5	0.44	
	I <sub>OL</sub> = 24 mA	5.5 V		0.36	0.5	0.44	
	I <sub>OL</sub> = 50 mA <sup>†</sup>	5.5 V			1.65	;	
	I <sub>OL</sub> = 75 mA <sup>†</sup>	5.5 V				1.65	
Control inputs	$V_{I} = V_{CC}$ or GND	5.5 V		±0.1	±1	±1	μA
OZ A or B ports‡	$V_0 = V_{CC}$ or GND	5.5 V		±0.5	±10	±5	μA
	$V_{I} = V_{CC} \text{ or } GND,  I_{O} = 0$	5.5 V		8	160	80	μA
C <sub>i</sub> Control inputs	$V_{I} = V_{CC}$ or GND	5 V		4.5			pF
C <sub>io</sub> A or B ports	$V_{O} = V_{CC}$ or GND	5 V		16			pF

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

<sup>‡</sup> For I/O ports, the parameter I<sub>OZ</sub> includes the input leakage current.

## timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted)

	PARAMETER			25°C	54AC16474		74AC16474		
				MAX	MIN	MAX	MIN	MAX	UNIT
fclock	clock Clock frequency								MHz
t <sub>su</sub>	t <sub>SU</sub> Setup time, data before CLK <sup>↑</sup>								ns
th	Hold time, data after CLK <sup>↑</sup>								ns
		High							
tw	Pulse duration	Low							ns

# timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted)

			T <sub>A</sub> = 2	25°C	54AC16474		74AC16474		
PARAMETER			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency								MHz
t <sub>su</sub>	t <sub>SU</sub> Setup time, data before CLK <sup>↑</sup>								ns
t <sub>h</sub>	Hold time, data after CLK <sup>↑</sup>								ns
		High							
tw	Pulse duration	Low							ns



SCAS399A – JANUARY 1992

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V

FROM		то	T <sub>A</sub> = 25°C		54AC16474		74AC16474			
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
fmax										MHz
<sup>t</sup> PLH										
<sup>t</sup> PHL	CLK	A or B								ns
<sup>t</sup> PZH										
<sup>t</sup> PZL		A . D								
<sup>t</sup> PHZ	ŌĒ	A or B						ns		
<sup>t</sup> PLZ										

## switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V

	FROM	то	Т	<b>₄ = 25°C</b>	;	54AC16474		74AC16474		
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
fmax										MHz
<sup>t</sup> PLH										
<sup>t</sup> PHL	CLK	A or B								ns
<sup>t</sup> PZH										
<sup>t</sup> PZL										
<sup>t</sup> PHZ	OE	A or B					ns			
<sup>t</sup> PLZ										

### operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = $25^{\circ}$ C

PARAMETER			TEST CON	TYP	UNIT	
		Outputs enabled				
Cpd	Power dissipation capacitance per transceiver	Outputs disabled	C <sub>L</sub> = 50 pF,	f = 1 MHz		pF



SCAS399A - JANUARY 1992



NOTES: A. CL includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>0</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  3 ns, t<sub>f</sub>  $\leq$  3 ns. For testing pulse duration: t<sub>r</sub> = t<sub>f</sub> = 1 to 3 ns. Pulse polarity can be either high-to-low-to-high or low-to-high-to-low.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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